



Click [here](#) for the 3D model.

General Information

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| Series | ESD SMD Comm COG |
| Style | SMD Chip |
| Description | SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I |
| Features | Temperature Stable, Low ESR, Class I |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 13 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Dimensions

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|-----------|-----------------|
| Chip Size | 0805 |
| L | 2mm +/-0.2mm |
| W | 1.25mm +/-0.2mm |
| T | 0.9mm +/-0.10mm |
| S | 0.7mm MIN |
| B | 0.5mm +/-0.25mm |

Packaging Specifications

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|--------------------|-----------|
| Packaging | Bulk, Bag |
| Packaging Quantity | 1 |

Specifications

| | |
|--|------------------------|
| Capacitance | 1,000 pF |
| Measurement Condition | 1 MHz 1.0Vrms |
| Tolerance | 1% |
| Voltage DC | 250 VDC |
| ESD Level per AEC-Q200 | 8,000 V ESD Level |
| Dielectric Withstanding Voltage | 625 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 MHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 100 GOHms |

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